Lead free solder　Product information

EVASOL　J3-3229-JK

Sn-Ag-Cu type、Lead free solder paste
RMA type、Non cleaning、Dispensable type

<Feature>

- Few solder ball at light beam soldering.
- Good Accurate dispensing stability.

Characteristics data

Test terms		Characteristic	Test method
Alloy composition（%）		Sn：Balance、Ag：3.0、Cu：0.5	Allowable impurity level is based on JIS Z 3282 class-A
Solidus temperature（℃）		217	DSC (Differential Scanning Calorimetry)
Liquidus temperature（℃）		220	
Powder particle size（μm）		45～25	Reference by JIS Z 3284 Annex 1
Flux contents (%)		14.0±0.5	Reference by JIS Z 3197 8.1.2
Halide content (%)		≦0.14	Reference by JIS Z 3197 8.1.4.2.1
Copper mirror test		Passed	Reference by JIS Z 3197 8.1.4.2
Copper plate corrosion test		Passed	Reference by JIS Z 3197 8.1.4.1
Insulation resistance test（Ω）		$\geqq 5.0\times10^{8}$	Reference by JIS Z 3197 8.5.3 JIS-2 type、85℃90RH%、1000h、DV100V in the chamber
Voltage-applied moisture resistance test	Insulation resistance（Ω）	$\geqq 5.0\times10^{8}$	Reference by JIS Z 3197 8.5.4 JIS-2 type、85℃90RH%、1000h、Applied DC48V、DV100V in the chamber
	Migration	No migration	
Dryness test		Passed	Reference by JIS Z 3197 8.5.1
Spreading ratio（%）		≧75	Reference by JIS Z 3197 8.3.1.1
Viscosity（Pa･s）		130±30	Reference by JIS Z 3284 Annex 6
Thixotropy index		0.65±0.05	
Tackiness test	Initial（N）	≧1.2	Reference by JIS Z 3284 Annex 9
	After 24 hour（N）	＜1.0	
Slump-in-printing	Pattern I	≦0.2	Reference by JIS Z 3284 Annex 7
	Pattern II	≦0.2	
Slump-in-heating	Pattern I	≦0.4	Reference by JIS Z 3284 Annex 8
	Pattern II	≦0.4	

*Above values are typical values.
*This solder paste includes non-ionic halide activator.